CLAIMS

[Claim 1]

A conductive paste composition comprising:

a (A) conductive powder; and

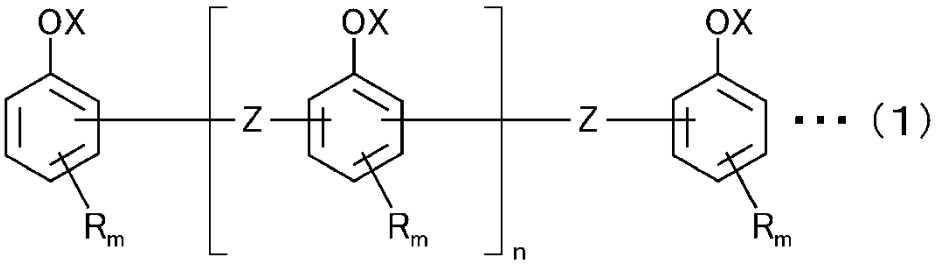
resin components, wherein

the resin components include a (B) epoxy resin, a (C) curing agent, and a (D) curing accelerator,

the (B) epoxy resin contains at least one type of epoxy resin having an epoxy equivalent of 500 g/eq or more, and

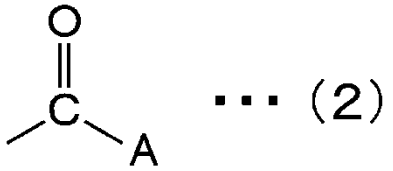
the (C) curing agent is a phenolic ester compound having a structure represented by the following general formula (1),

[Chem. 1]



provided that R in the formula (1) represents an alkyl group having 1 to 10 carbon atoms, a substituted or unsubstituted phenyl group, a substituted or unsubstituted aralkyl group, an alkoxy group, or a halogen atom, X in the formula (1) represents a hydrogen atom or an ester structure represented by the following general formula (2), A in the formula (2) represents an alkyl group having 1 to 6 carbon atoms,

[Chem. 2]



Z in the formula (1) represents a divalent hydrocarbon group having 1 to 15 carbon atoms, m in the formula (1) represents an integer of 0 to 4, n in the formula (1) represents a number of 0 to 2 on average, R, X, and Z in the formula (1) and A in the formula (2) may represent the same substituent or atom or may represent different substituents or atoms, and m

in the formula (1) may represent the same integer or may represent different integers.

[Claim 2]

The conductive paste composition according to claim 1, wherein

the (B) epoxy resin contains 30 mass% or more of the epoxy resin having the epoxy equivalent of 500 g/eq or more.

[Claim 3]

The conductive paste composition according to claim 1, wherein

an esterification rate of the (C) curing agent is 70% or more.

[Claim 4]

The conductive paste composition according to claim 1, wherein

the (C) curing agent is compounded in an amount within a range of 3 parts by mass to 150 parts by mass per 100 parts by mass of the (B) epoxy resin.

[Claim 5]

The conductive paste composition according to claim 1, wherein

the (A) conductive powder includes at least one selected from the group consisting of silver powder, copper powder, silver-coated copper powder, silver-coated nickel powder, silver-coated aluminum powder, and silver-coated glass powder.

[Claim 6]

The conductive paste composition according to any one of claims 1 to 5, which is used by being applied to a base material by a printer, a dispenser, or by dipping.

[Claim 7]

The conductive paste composition according to any one of claims 1 to 5, which is used by being applied to an electrode of an electronic component.